



限用物質含有情況標示聲明書

Declaration of the Presence Condition of the Restricted Substances Marking

設備名稱： 鑽石鑽孔機 ， 型號（型式）： DD 200 Equipment name Type designation (Type)						
單元 Unit	限用物質及其化學符號 Restricted substances and its chemical symbols					
	鉛Lead (Pb)	汞Mercury (Hg)	鎘Cadmium (Cd)	六價鉻 Hexavalent chromium (Cr ⁺⁶)	多溴聯苯 Polybrominate d biphenyls (PBB)	多溴二苯醚 Polybrominated diphenyl ethers (PBDE)
電子原件 (電路版, 開關, 電 線) Electronics (pcb, switch, wiring)	—	○	—	○	○	○
馬達 Motor	—	○	○	○	○	○
電源線 Power cord	—	○	○	○	○	○
緊固元件 Fastener elements	○	○	○	○	○	○
金屬部件 Metal parts	—	○	○	○	○	○
電源供應系統 Power supplies	—	○	○	○	○	○

備考1. “超出0.1 wt %” 及 “超出0.01 wt %” 係指限用物質之百分比含量超出百分比含量基準值。

Note 1 : “Exceeding 0.1 wt %” and “exceeding 0.01 wt %” indicate that the percentage content of the restricted substance exceeds the reference percentage value of presence condition.

備考2. “○” 係指該項限用物質之百分比含量未超出百分比含量基準值。

Note 2 : “○” indicates that the percentage content of the restricted substance does not exceed the percentage of reference value of presence.

備考3. “—” 係指該項限用物質為排除項目。

Note 3 : The “—” indicates that the restricted substance corresponds to the exemption.